CLAIM AMENDMENTS:

Claims 1-30 (Canceled).

Claim 31 (Currently Amended): A semiconductor device, comprising:

a substrate having an upper surface including a chip mounting region, a wiring region and a reinforcement layer region, the regions being independent from each other, the wiring region being located outside of the chip mounting region, the reinforcement layer region being located outside of the wiring region;

wiring formed in the wiring region;

a reinforcement layer formed in the reinforcement layer region;

a protective film that is a solder resist, and that is in direct contact with the substrate, and covers the substrate, the wiring and the reinforcement layer to protect them;

a semiconductor chip arranged over the chip mounting region and on the protective film;

a bonding wire that connects the semiconductor chip to the wiring; and

a sealing resin that seals at least the bonding wire and the semiconductor chip;

wherein the protective film is disposed under the semiconductor chip, and wherein an upper surface of the protective film is not planar over the wiring and the reinforcement layer, and is planar under the semiconductor chip.

Claim 32 (Previously Presented): The semiconductor device of claim 31, wherein the protective film has a shape corresponding to the surfaces of the wiring, the reinforcement layer and the substrate.

Claim 33 (Previously Presented): The semiconductor device of claim 31, further comprising solder balls provided on a rear surface of the substrate.

Claim 34 (Previously Presented): The semiconductor device of claim 33, wherein the solder balls are electrically connected with the wiring.

Claim 35 (Previously Presented): The semiconductor device of claim 31, wherein the wiring comprises copper.

Claim 36 (Previously Presented): The semiconductor device of claim 33, wherein the solder balls are provided at positions on the rear surface of the substrate corresponding to the wiring region.

Claim 37 (Canceled).

Claim 38 (Previously Presented): The semiconductor device of claim 31, wherein a surface of a portion of the protective film positioned in the chip mounting region is planar.

Claim 39 (Previously Presented): The semiconductor device of claim 31, wherein none of the wiring is covered by the semiconductor chip.

Claim 40 (Currently Amended): The semiconductor device of claim 31, wherein the protective film ~~is disposed under the semiconductor chip and~~ supports the semiconductor chip over the chip mounting region, with the semiconductor chip being separated from the wiring and from the surface of the substrate by the protective film.

Claim 41 (Previously Presented): The semiconductor device of claim 31, wherein the semiconductor chip has a terminal on an upper surface thereof; and wherein said bonding wire that extends from the terminal to the wiring to electrically connect the semiconductor chip to the wiring.

Claims 42 and 43 (Canceled).

Claim 44 (Currently Amended): A semiconductor device, comprising:

a substrate having an upper surface including a chip mounting region, a wiring region and a reinforcement layer region, the regions being independent from each other, the wiring region being located outside of the chip mounting region, the reinforcement layer region being located outside of the wiring region;

wiring formed in the wiring region;

a reinforcement layer formed in the reinforcement layer region;

a protective film that covers the substrate, the wiring and the reinforcement layer to protect them;

a semiconductor chip arranged over the chip mounting region and on the protective film;

a bonding wire that connects the semiconductor chip to the wiring; ~~and~~

a sealing resin that covers the semiconductor chip and seals at least the bonding wire and the semiconductor chip; and

solder balls provided on a rear surface of the substrate;

wherein the protective film has a shape corresponding to the surfaces of the wiring, the reinforcement layer and the substrate;

wherein the solder balls are electrically connected with the wiring;

wherein the wiring comprises copper;

wherein the solder balls are provided at positions on the rear surface of the substrate corresponding to the wiring region;

wherein the protective film is a solder resist;

wherein a surface of a portion of the protective film positioned in the chip mounting region is planar;

wherein none of the wiring is covered by the semiconductor chip;

wherein the protective film is disposed under the semiconductor chip and supports the semiconductor chip over the chip mounting region, with the semiconductor chip being separated from the wiring and from the surface of the substrate by the protective film;

wherein the semiconductor chip has a terminal on an upper surface thereof;

wherein said bonding wire extends from the terminal to the wiring to electrically connect the semiconductor chip to the wiring; and

wherein an upper surface of the protective film is not planar over the wiring and the reinforcement layer, and is planar under the semiconductor chip.

Claim 45 (Canceled).

Claim 46 (Currently Amended): A semiconductor device, comprising:

a substrate having an upper surface including a chip mounting region, a wiring region and a reinforcement layer region, the regions being independent from each other, the wiring region being located outside of the chip mounting region, the reinforcement layer region being located outside of the wiring region;

wiring formed in the wiring region;

a reinforcement layer formed in the reinforcement layer region;

a protective film that covers the substrate, the wiring and the reinforcement layer to protect them;

a semiconductor chip arranged over the chip mounting region and on the protective film;

a bonding wire that connects the semiconductor chip to the wiring;

a sealing resin that seals at least the bonding wire and the semiconductor chip; and

solder balls disposed on a lower surface of said substrate,

wherein said substrate is disposed over the solder balls, and under the wiring, the reinforcement layer, and the semiconductor chip;

wherein the protective film is in direct contact with the substrate, and has a shape corresponding to the surfaces of the wiring, the reinforcement layer and the substrate;

wherein the solder balls are electrically connected with the wiring;

wherein the wiring comprises copper;

wherein the solder balls are provided at positions on the rear surface of the substrate corresponding to the wiring region;

wherein the protective film is a solder resist;

wherein a surface of a portion of the protective film positioned in the chip mounting region is planar;

wherein none of the wiring is covered by the semiconductor chip;

wherein the protective film is disposed under the semiconductor chip and supports the semiconductor chip over the chip mounting region, with the semiconductor chip being separated from the wiring and from the surface of the substrate by the protective film;

wherein the semiconductor chip has a terminal on an upper surface thereof;

wherein said bonding wire extends from the terminal to the wiring to electrically connect the semiconductor chip to the wiring;

wherein an upper surface of the protective film is not planar over the wiring and the reinforcement layer, and is planar under the semiconductor chip; and

wherein the sealing resin covers the semiconductor chip.

Claim 47 (Canceled).